

Technical Specification

- 10GBASE Copper RJ45 30m HP/Aruba Compatible

SFP to Host Connector Pin Out

Pin	Symbol	Name/Description	Ref.
1	V_{EET}	Transmitter Ground (Common with Receiver Ground)	1
2	T_{FAULT}	Transmitter Fault.	2
3	T_{DIS}	Transmitter Disable. Laser output disabled on high or open.	3
4	SDA	2-wire Serial Interface Data Line	4
5	SCL	2-wire Serial Interface Clock Line	4
6	MOD_ABS	Module Absent. Grounded within the module	4
7	RS0	Rate Select 0	5
8	LOS	Loss of Signal indication. Logic 0 indicates normal operation.	6
9	RS1	No connection required	1
10	V_{EER}	Receiver Ground (Common with Transmitter Ground)	1
11	V_{EER}	Receiver Ground (Common with Transmitter Ground)	1
12	RD-	Receiver Inverted DATA out. AC Coupled	
13	RD+	Receiver Non-inverted DATA out. AC Coupled	
14	V_{EER}	Receiver Ground (Common with Transmitter Ground)	1
15	V_{CCR}	Receiver Power Supply	
16	V_{CCT}	Transmitter Power Supply	
17	V_{EET}	Transmitter Ground (Common with Receiver Ground)	1
18	TD+	Transmitter Non-Inverted DATA in. AC Coupled.	
19	TD-	Transmitter Inverted DATA in. AC Coupled.	
20	V_{EET}	Transmitter Ground (Common with Receiver Ground)	1

Notes:

- 1) Circuit ground is internally isolated from chassis ground.
- 2) T_{FAULT} is an open collector/drain output, which should be pulled up with a 4.7k – 10k Ohms resistor on the host board if intended for use. Pull up voltage should be between 2.0V to $V_{cc} + 0.3V$. A high output indicates a transmitter fault caused by either the TX bias current or the TX output power exceeding the preset alarm thresholds. A low output indicates normal operation. In the low state, the output is pulled to <0.8V.
- 3) Laser output disabled on $T_{DIS} > 2.0V$ or open, enabled on $T_{DIS} < 0.8V$.
- 4) Should be pulled up with 4.7kΩ- 10kΩ host board to a voltage between 2.0V and 3.6V. MOD_ABS pulls line low to indicate module is plugged in.
- 5) Internally pulled down per SFF-8431 Rev 4.1.

- 6) LOS is open collector output. It should be pulled up with 4.7kΩ – 10kΩ on host board to a voltage between 2.0V and 3.6V. Logic 0 indicates normal operation; logic 1 indicates loss of signal.

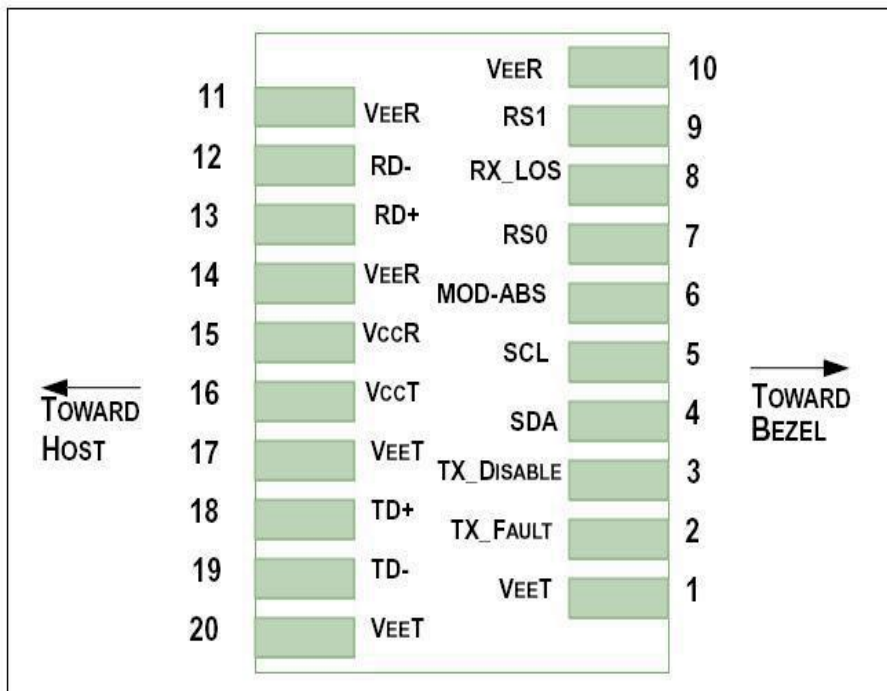


Figure 1. Diagram of host board connector block pin numbers and names

5. +3.3V Volt Electrical Power Interface

The SFP+-10GBASE-T has an input voltage range of 3.3 V +/- 5%. The 4V maximum voltage is not allowed for continuous operation.

+3.3 Volt Electrical Power Interface						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Supply Current	Is		700	900	mA	3.0W max power over full range of voltage and temperature. See caution note below
Input Voltage	Vcc	3.13	3.3	3.47	V	Referenced to GND
Maximum Voltage	Vmax			4	V	
Surge Current	Isurge		TBD		mA	Hot plug above steady state current. See caution note below

Caution: Power consumption and surge current are higher than the specified values in the SFP MSA

6. Low-Speed Signals

MOD_DEF(1) (SCL) and MOD_DEF(2) (SDA), are open drain CMOS signals (see section VII, "Serial Communication Protocol"). Both MOD_DEF(1) and MOD_DEF(2) must be pulled up to host_Vcc

Low-Speed Signals, Electronic Characteristics					
Parameter	Symbol	Min	Max	unit	Notes/Conditions
SFP Output LOW	VOL	0	0.5	V	4.7k to 10k pull-up to host_Vcc, measured at host side of connector
SFP Output HIGH	VOH	host_Vcc -0.5	host_Vcc + 0.3	V	4.7k to 10k pull-up to host_Vcc, measured at host side of connector
SFP Input LOW	VIL	0	0.8	V	4.7k to 10k pull-up to Vcc, measured at SFP side of connector
SFP Input HIGH	VIH	2	Vcc + 0.3	V	4.7k to 10k pull-up to Vcc, measured at SFP side of connector

7. High-Speed Electrical Interface

All high-speed signals are AC-coupled internally.

High-Speed Electrical Interface Transmission Line-SFP						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Line Frequency	fL		125		MHz	5-level encoding, per IEEE 802.3
Tx Output Impedance	Zout,TX		100		Ohm	Differential, for all frequencies between 1MHz and 125MHz
Rx Input Impedance	Zin,RX		100		Ohm	Differential, for all frequencies between 1MHz and 125MHz

High-Speed Electrical Interface, Host-SFP						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Single ended data input swing	Vinsing	250		1200	mV	Single ended
Single ended data output swing	Voutsing	350		800	mV	Single ended
Rise/Fall Time	T _r , T _f		175		psec	20%-80%
Tx Input Impedance	Zin		50		Ohm	Single ended
Rx Output Impedance	Zout		50		Ohm	Single ended

8. General Specifications

General						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Data Rate	BR	1		10	Gb/sec	IEEE 802.3 compatible. See Notes 1,2 below

Notes:

1. Clock tolerance is +/- 50 ppm

9. Environmental Specifications

Automatic crossover detection is enabled. External crossover cable is not required

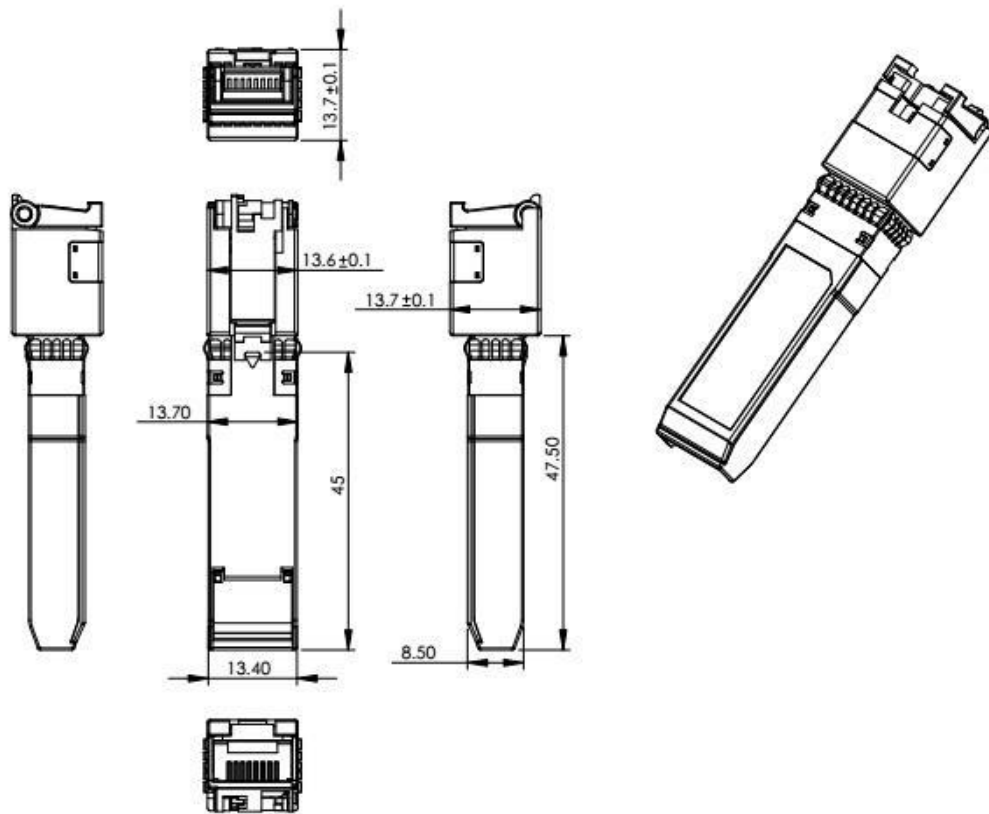
Environmental Specifications						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
Operating Temperature	Top	0		65	°C	Case temperature
Storage Temperature	Tsto	-40		85	°C	Ambient temperature

10. Serial Communication Protocol

ETU series' SFPs support the 2-wire serial communication protocol outlined in the SFP MSA. These SFPs use an MCU, can be accessed with address of A0h.

Serial Bus Timing, Requirements						
Parameter	Symbol	Min	Typ	Max	unit	Notes/Conditions
I ² c Clock Rate		0		200,000	Hz	

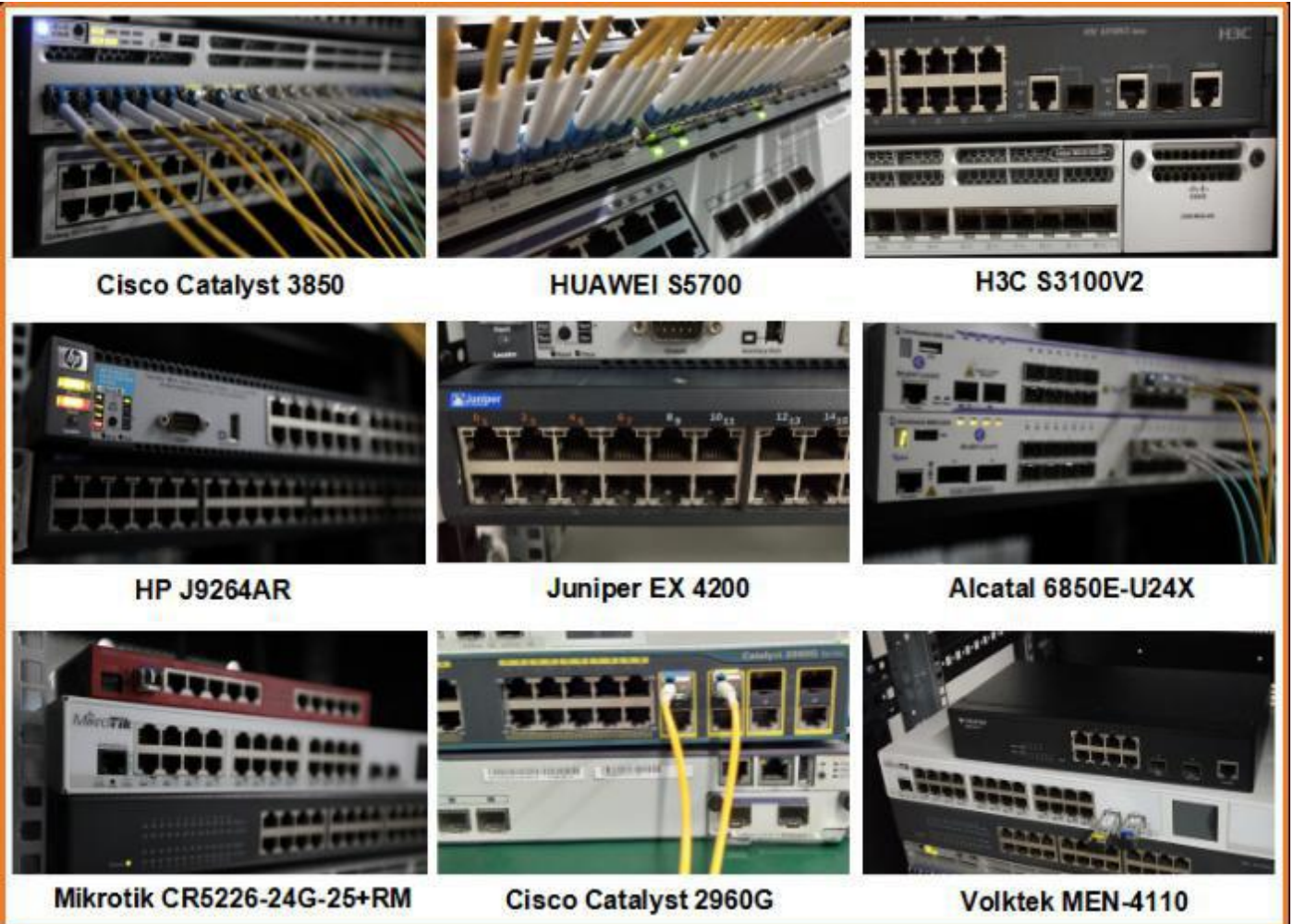
11. Mechanical Specifications (Unit:mm)



Compatibility Test

In order to ensure the product compatibility, our products will be tested on the switch before shipment. Our modules can compatible with many mainstream brand switches, such as Cisco, Juniper, Extreme, Brocade, IBM, H3C, HP, Huawei, D-Link, Mikrotik, ZTE, TP-Link...

Our test equipment: VOLKTEK MEN-4110, HP 2530-8G, CRS226-24G-25+RM, Catalyst 2960G Series, Catalyst 3850 XS 10G SFP+, Catalyst 3750-E Series, HUAWEI S5700Series, H3C S3100V2 Series, Juniper-EX4200, etc.



Product Production Process

Quality Assurance

Continuous introduction of new equipment, produced by strict standards, strict quality inspection, to guarantee the high quality standard of each product.



**Standardized
Production Line**



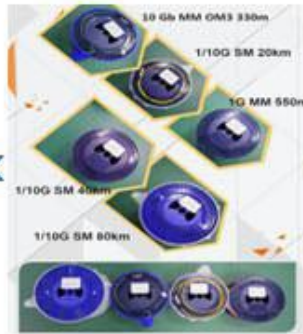
**Professional
Welding**



Assembling



Aging Testing



Distance Testing



Cleaning end face



Product Initial Test



Switch Testing



Product Final Test

